

SOT-23 Plastic-Encapsulate MOSFETS

RC02N10T3

N-Channel 100-V(D-S) MOSFET

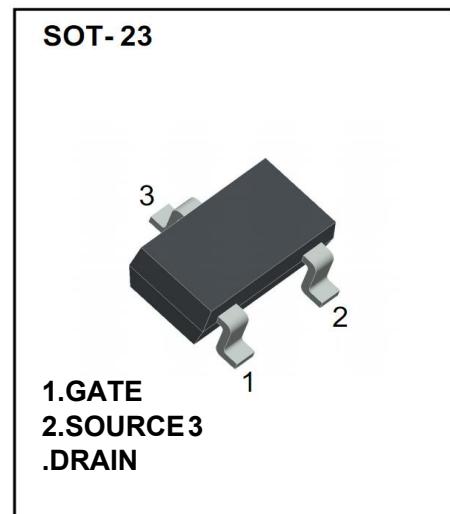
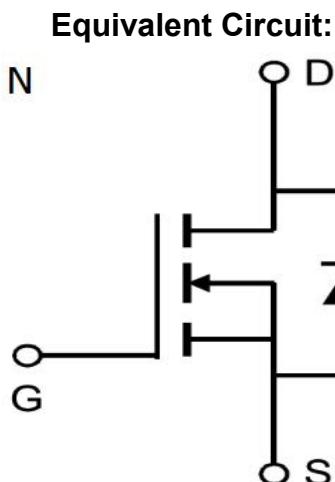
V(BR)DSS	RDS(on)MAX	ID
100 V	6Ω@10V	0.17A
	10Ω@4.5V	

FEATURE:

- Rugged and Reliable
- High density cell design for extremely low RDS(on)
- Surface Mount Package
- Voltage Controlled Small Signal Switch

APPLICATION:

- ※ Small Servo Motor Controls
- ※ Power MOSFET Gate Drivers
- ※ Switching Application



Mosfet Maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	VDS	100	V
Gate-Source Voltage	VGS	±20	
Continuous Drain Current	ID	0.17	A
Pulsed Drain Current (tp=10us)	IDM	0.68	A
Continuous Source-Drain Current(Diode Conduction)	IS	0.17	A
Power Dissipation	PD	0.35	W
Thermal Resistance from Junction to Ambient	R _{θJA}	357	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~+150	°C
Lead Temperature for Soldering Purposes(1/8 from case for	TL	260	°C

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MOSFET ELECTRICAL CHARACTERISTICS

unless otherwise specified $T_a = 25^\circ\text{C}$

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V(BR)DSS	$V_{GS} = 0V, ID = 250\mu\text{A}$	100			V
Gate-threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, ID = 250\mu\text{A}$	1		2.8	V
Gate-body leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 50	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 100V, V_{GS} = 0V$			1	μA
Drain-source on-resistancea	RDS(on)	$V_{GS} = 10V, ID = 0.17\text{A}$		3.8	6	Ω
		$V_{GS} = 4.5V, ID = 0.17\text{A}$		3.5	10	Ω
Forward transconductancea	g_{fs}	$V_{DS} = 10V, ID = 170\text{mA}$	80			ms
Diode forward voltage	V_{SD}	$IS=0.17\text{A}, V_{GS}=0V$		0.8	1.3	V
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{DS} = 25V, V_{GS} = 0V, f = 1\text{MHz}$		29		pF
Output capacitance	C_{oss}			10		pF
Reverse transfer capacitanceb	C_{rss}			2		pF
Switchingb Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 30V, ID = 0.17\text{A}, R_{GEN} = 50\Omega$			8	ns
Rise time	t_r				8	ns
Turn-off delay time	$t_{d(off)}$				13	ns
Fall time	t_f				16	ns
Total Gate Charge	Q_g	$V_{DS} = 10V, ID = 0.17\text{A}, V_{GS} = 10V$			2	nC
Gate-Source Charge	Q_{gs}				0.25	nC
Gate-Drain Charge	Q_{gd}				0.4	nC

Note :

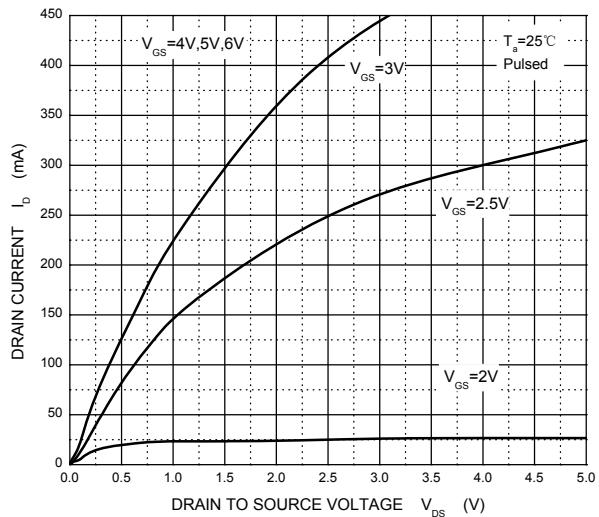
1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test ; Pulse Width = $300\mu\text{s}$, Duty Cycle $\leq 2\%$.
3. Switching characteristics are independent of operating junction temperature.
4. Guaranteed by design, not subject to producing.

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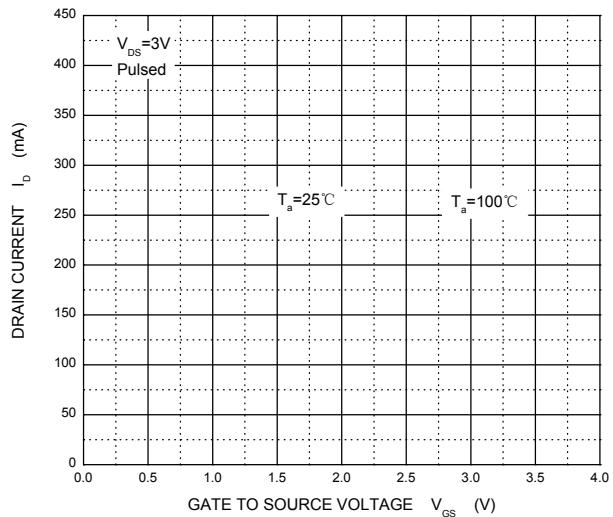
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Typical Characteristics

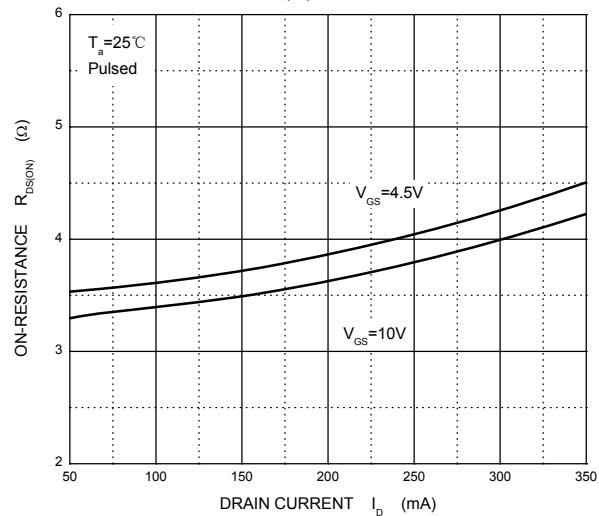
Output Characteristics



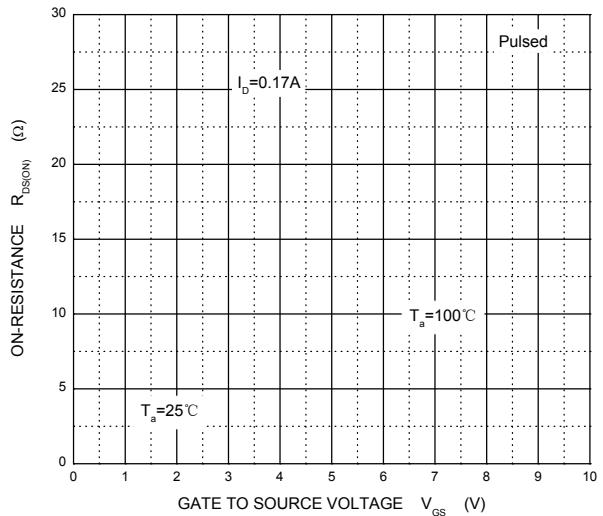
Transfer Characteristics



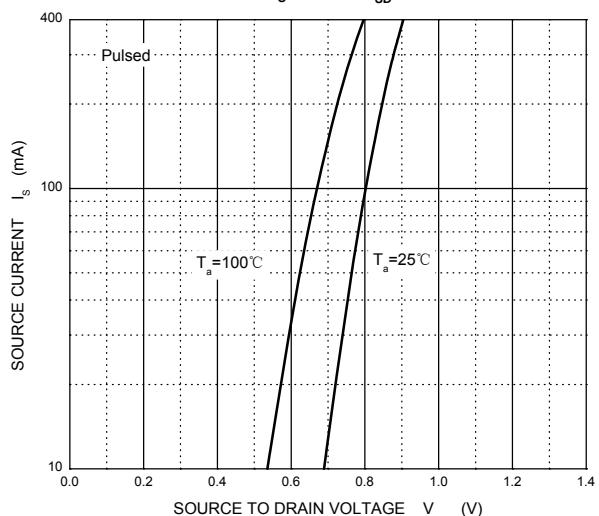
$R_{DS(ON)}$ — I_D



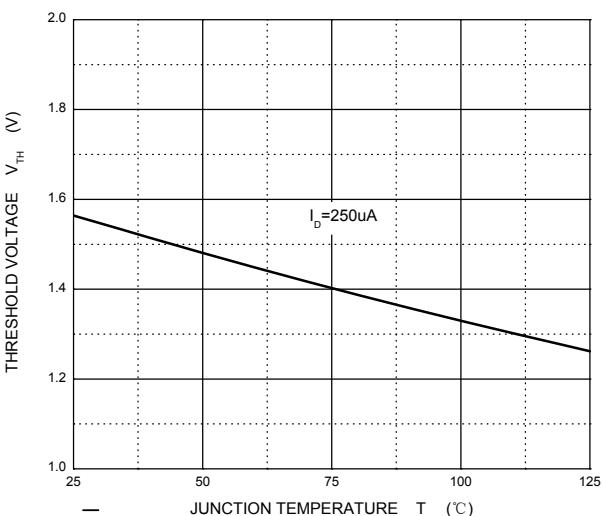
$R_{DS(ON)}$ — V_{GS}



I_S — V_{SD}



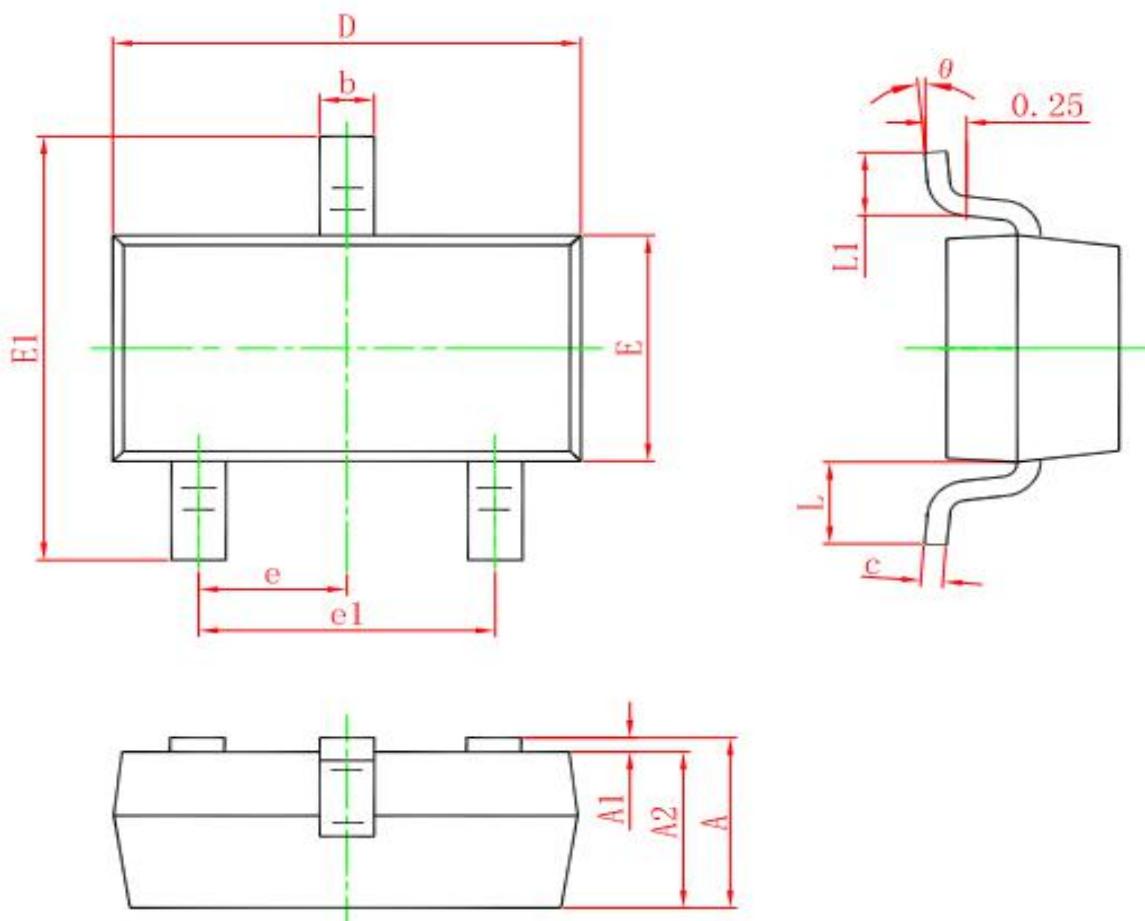
Threshold Voltage



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SOT-23 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°